
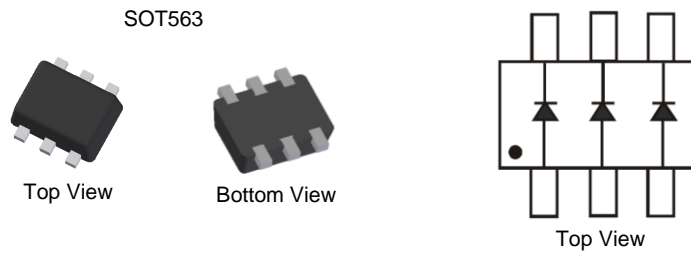


Features

- Fast Switching Speed
- Low Forward Voltage: Maximum of 0.715V at 1mA
- Fast Reverse Recovery: Maximum of 4ns
- Low Capacitance: Maximum of 1.5pF
- Low Leakage Current
- Ultra-Small Surface Mount Package
- Thermally Efficient Copper Alloy Leadframe for High Power Dissipation
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: SOT563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Alloy Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 
- Weight: 0.003 grams (Approximate)

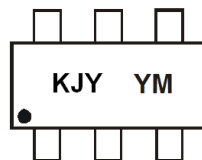


Ordering Information (Note 4)

Part Number	Case	Packaging
BAS16VA-7	SOT563	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3).compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



KJY = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: F = 2018)
 M = Month (ex: 9 = September)

Date Code Key

Year	2018	2019	2020	2021	2022	2023	2024
Code	F	G	H	I	J	K	L

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = 25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	71	V
Forward Continuous Current (Note 5)	I _{FM}	200	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	@ t = 1.0µs	4.0
		@ t = 1.0ms	1.0
		@ t = 1.0s	0.5

Thermal Characteristics (@T_A = 25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = 25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	100	—	V	I _R = 100µA
Forward Voltage	V _F	—	0.715	V	I _F = 1.0mA
		—	0.855		I _F = 10mA
		—	1.0		I _F = 50mA
		—	1.25		I _F = 150mA
Leakage Current (Note 6)	I _R	—	0.5	µA	V _R = 80V
		—	50	µA	V _R = 80V, T _J = 125°C
		—	30	µA	V _R = 25V, T _J = 125°C
		—	30	nA	V _R = 25V
Total Capacitance	C _T	—	1.5	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

Notes: 5. Device mounted on FR-4 PCB, on minimum recommended 2oz copper pad layout.
6. Short duration pulse test used to minimize self-heating effect.

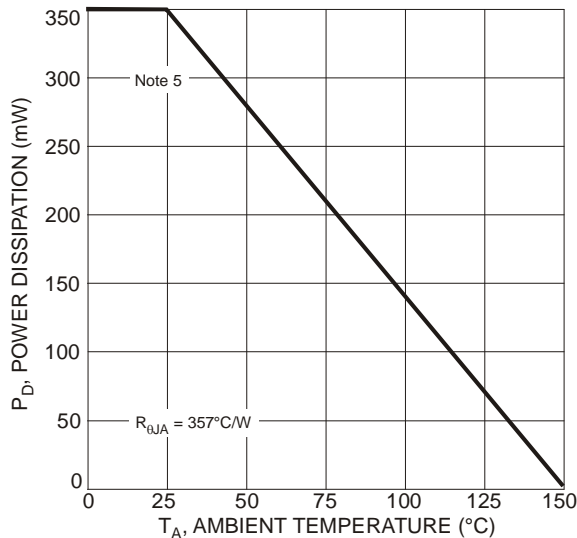


Fig. 1 Power Derating Curve, Total Package

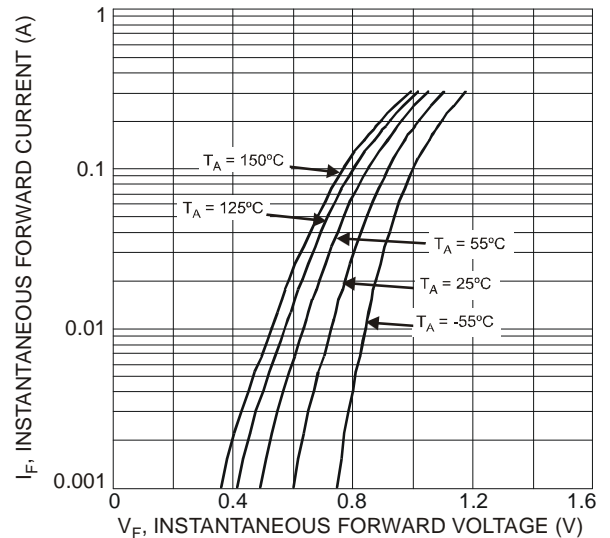


Fig. 2 Typical Forward Characteristics, Per Element

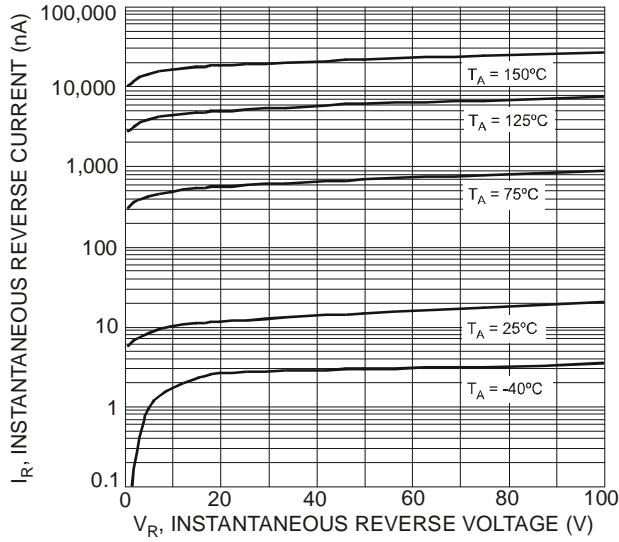


Fig. 3 Typical Reverse Characteristics, Per Element

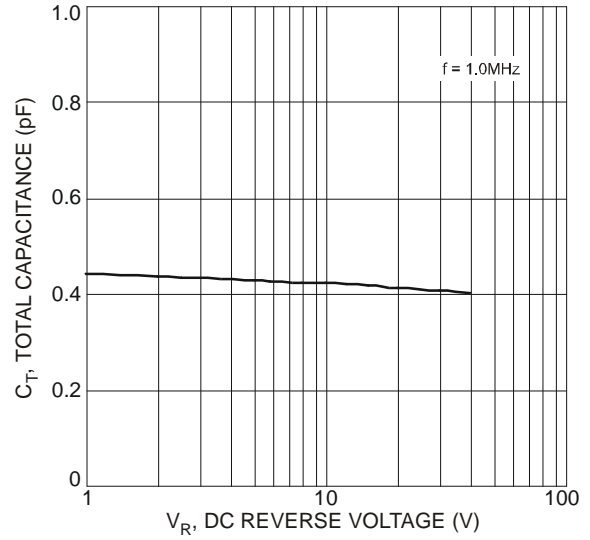
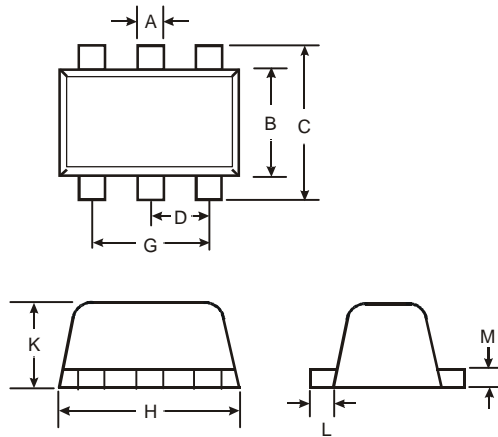


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

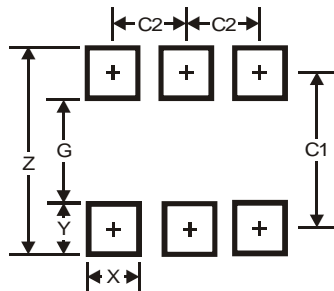
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



SOT563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

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